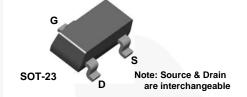


January 2015

# MMBFJ309 / MMBFJ310 N-Channel RF Amplifier

## **Description**

This device is designed for VHF/UHF amplifier, oscillator and mixer applications. As a common gate amplifier, 16 dB at 100 MHz and 12 dB at 450 MHz can be realized. Sourced from process 92. Source & Drain are interchangeable.



## **Ordering Information**

Part Number	Top Mark	Package	Packing Method
MMBFJ309	6U	SOT-23 3L	Tape and Reel
MMBFJ310	6T	SOT-23 3L	Tape and Reel

## Absolute Maximum Ratings(1), (2)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^{\circ}\text{C}$  unless otherwise noted.

Symbol	Parameter	Value	Unit
$V_{DG}$	Drain-Gate Voltage	25	V
$V_{GS}$	Gate-Source Voltage	-25	V
$I_{GF}$	Forward Gate Current	10	mA
$T_J$ , $T_{STG}$	Operating and Storage Junction Temperature Range	-55 to 150	°C

#### Notes:

- 1. These ratings are based on a maximum junction temperature of 150°C.
- These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty-cycle operations.

### Thermal Characteristics(3)

Values are at T<sub>A</sub> = 25°C unless otherwise noted.

Symbol	Parameter	Max.	Unit
P <sub>D</sub>	Total Device Dissipation	350	mW
	Derate Above 25°C	2.8	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	357	°C/W

#### Note:

3. Device mounted on FR-4 PCB 36mm × 18mm × 1.5mm; mounting pad for the collector lead minimum 6cm<sup>2</sup>.

## **Electrical Characteristics**

Values are at  $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter Conditions		Min.	Тур.	Max.	Unit	
Off Chara	acteristics				I	I	
V <sub>(BR)GSS</sub>	Gate-Source Breakdown Voltage	$I_G = -1.0 \mu\text{A},  V_{DS} = 0$		-25			V
I <sub>GSS</sub>	Cata Bayaraa Currant	$V_{GS} = -15 \text{ V}, V_{DS} = 0$				-1.0	nA
	Gate Reverse Current	V <sub>GS</sub> = -15 V, V <sub>DS</sub> = 0, T <sub>A</sub> = 125°C				-1.0	μΑ
	Cata Cauras Cut O# \/altaga	V 40 V I 40 m	MMBFJ309	-1.0		-4.0	V
V <sub>GS(off)</sub>	Gate-Source Cut-Off Voltage	$V_{DS} = 10 \text{ V}, I_{D} = 1.0 \text{ nA}$ MMBFJ310		-2.0		-6.5	'
On Chara	ncteristics						
I <sub>DSS</sub>	Zero-Gate Voltage Drain	$V_{DS} = 10 \text{ V}, V_{GS} = 0$	MMBFJ309	12		30	mA
DSS	Current <sup>(4)</sup>	VDS = 10 V, VGS = 0	MMBFJ310	24		60	mA
$V_{GS(f)}$	Gate-Source Forward Voltage	$V_{DS} = 0$ , $I_{G} = 1.0 \text{ mA}$				1.0	V
Small Sig	nal Characteristics						
Re <sub>(yis)</sub>	Common-Source Input Conductance	$V_{DS} = 10 \text{ V}, I_{D} = 10 \text{ mA},$	MMBFJ309		0.7		mmhos
		f = 100 MHz	MMBFJ310		0.5		
Re <sub>(yos)</sub>	Common-Source Output Conductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 10 mA, f = 100 MHz			0.25		mmhos
G <sub>pg</sub>	Common-Gate Power Gain	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 10 mA, f = 100 MHz			16		dB
Re <sub>(yfs)</sub>	Common-Source Forward Transconductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 10 mA, f = 100 MHz			12		mmhos
Re <sub>(yig)</sub>	Common-Gate Input Conductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 10 mA, f = 100 MHz			12		mmhos
	Common-Source Forward	$V_{DS} = 10 \text{ V}, I_{D} = 10 \text{ mA}, MI$	MMBFJ309	10000		20000	umboo
9 <sub>fs</sub>	Transconductance $f = 1.0 \text{ kHz}$		MMBFJ310	8000		18000	μmhos
g <sub>oss</sub>	Common-Source Output Conductance	$V_{DS} = 10 \text{ V}, I_{D} = 10 \text{ mA}, I_{D} = 10 \text{ mA}$	f = 1.0 kHz			150	μmhos
~	Common-Gate Forward Conductance	$V_{DS} = 10 \text{ V}, I_{D} = 10 \text{ mA},$	MMBFJ309		13000		μmhos
$g_{fg}$		f = 1.0 kHz	MMBFJ310		12000		
a	Common-Gate Output Conductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 10 mA, MMBFJ309 f = 1.0 kHz MMBFJ310	MMBFJ309		100		umbos
$g_{og}$				150		μmhos	
C <sub>dg</sub>	Drain-Gate Capacitance	$V_{DS} = 0$ , $V_{GS} = -10 \text{ V}$ , $f = 1.0 \text{ MHz}$			2.0	2.5	pF
C <sub>sg</sub>	Source-Gate Capacitance	$V_{DS} = 0$ , $V_{GS} = -10$ V, $f = 1.0$ MHz			4.1	5.0	pF
NF	Noise Figure	$V_{DS} = 10 \text{ V}, I_{D} = 10 \text{ mA}, f = 450 \text{ MHz}$			3.0		dB
e <sub>n</sub>	Equivalent Short-Circuit Input Noise Voltage	$V_{DS} = 10 \text{ V}, I_{D} = 10 \text{ mA}, t$	f = 100 Hz		6.0		nV://Hz

## Note:

4. Pulse test: pulse width  $\leq 300~\mu s,~duty~cycle \leq 2.0\%$ 

## **Typical Performance Characteristics**

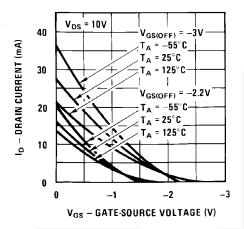


Figure 1. Transfer Characteristics

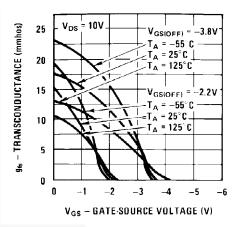


Figure 3. Transfer Characteristics

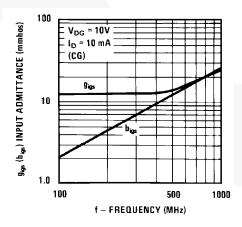


Figure 5. Input Admittance

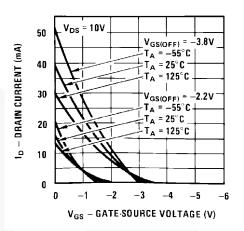
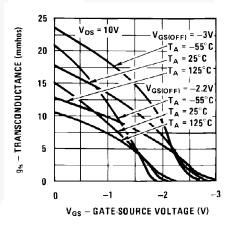


Figure 2. Transfer Characteristics



**Figure 4. Transfer Characteristics** 

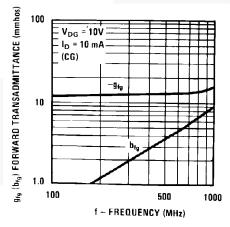


Figure 6. Forward Transadmittance

## **Typical Performance Characteristics** (Continued)

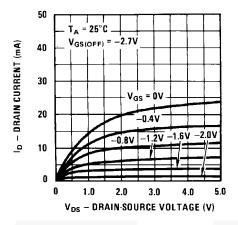
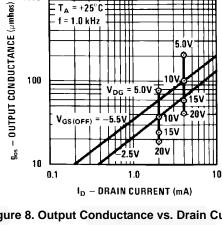


Figure 7. Common Drain-Source



1000

Figure 8. Output Conductance vs. Drain Current

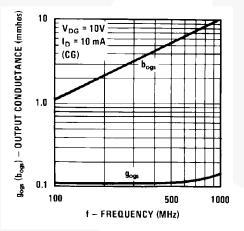


Figure 9. Output Admittance

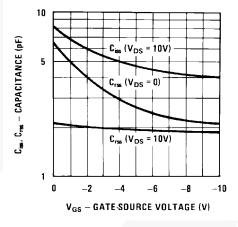


Figure 10. Capacitance vs. Voltage

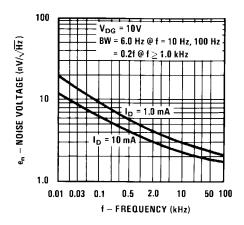


Figure 11. Noise Voltage vs. Frequency

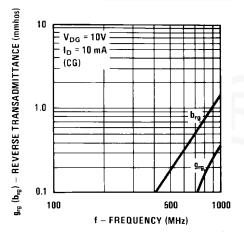


Figure 12. Reverse Transadmittance

## **Typical Performance Characteristics** (Continued)

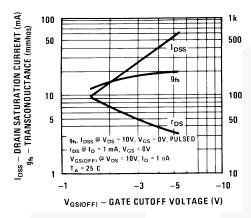


Figure 13. Parameter Interactions

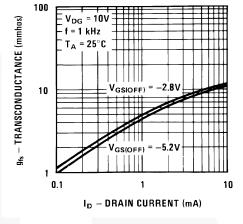


Figure 14. Transconductance vs. Drain Current

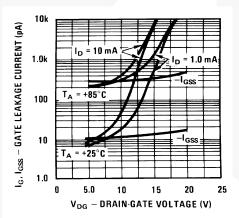


Figure 15. Leakage Current vs. Voltage

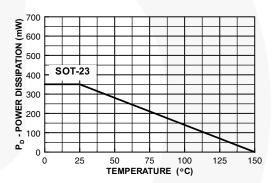
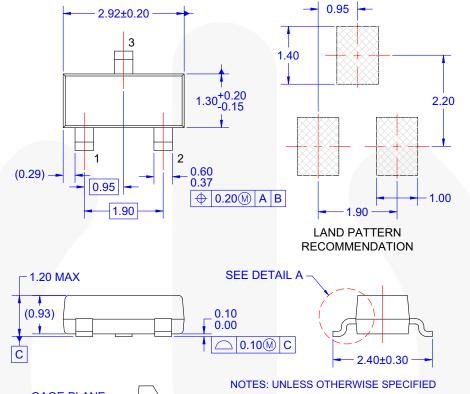


Figure 16. Power Dissipation vs. Ambient Temperature

## **Physical Dimensions**



- 0.23 0.08 0.25 0.20 MIN SEATING PLANE
- A) REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE H.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE INCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M 1994.
- SEATING E) DRAWING FILE NAME: MA03DREV10



Figure 17. 3-LEAD, SOT23, JEDEC TO-236, LOW PROFILE





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No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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